

02-15-2000

24 JAN 2000



ET 1-24-00 Patent and Trademark Office

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To the Honorable Commissioner of Patents

documents or copy thereof.

1. Name of conveying party(ies):
Ralf Boehnke, Kentaro Odaka, Hamid Amir-Alikhani, Richard Stirling-Gallacher, Seiichi Izumi, and Mitsuhiro Suzuki
Additional name(s) of conveying party(ies) attached? Yes No

Name and address of receiving party(ies):
Name: Sony Corporation
Internal Address: _____

3. Nature of Conveyance:
 Assignment Merger
 Security Agreement Change of Name
 Other _____
Execution Date: December 20, 1999 and January 10, 2000

Street Address: 7-35 Kitashinagawa 6-chome
Shinagawa-ku, Tokyo, Japan
City _____ State _____ ZIP _____
Additional name(s) & address(es) attached? Yes No

4. Application number(s) or patent number(s):
If this document is being filed together with a new application, the execution date of the application is:
A. Patent Application No.(s)
09/402,637
Additional numbers attached? Yes No

B. Patent No.(s)
 Yes No

5. Name and address of party to whom correspondence concerning document should be mailed:
Name: Jay H. Maioli
Internal Address: Cooper & Dunham LLP

Street Address: 1185 Avenue of the Americas

City: New York State: New York ZIP: 10036

6. Total number of applications and patents involved: 1
7. Total fee (37 CFR 3.41): \$ 40.00
 Enclosed
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9. Statement and signature.
To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.
Jay H. Maioli, Reg. No. 27,213 Jay H. Maioli January 20, 2000
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2. Sony International (Europe) G.m.b.H.
Hugo-Eckener-Str. 20, D-50829,
Koeln-Ossendorf, Germany

ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in TRANSMITTING METHOD, RECEIVING METHOD, TRANSMITTER, AND RECEIVER for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 6-7-35 Kitashinagawa, Shinagawa-Ku, Tokyo, Japan and Sony International (Europe) G.m.b.H, with offices at Hugo-Eckener-Str. 20, D-50829, Koeln-Ossendorf, Germany, (hereinafter referenced as ASSIGNEES) are desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEES, their successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEES, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEES or their designee, as ASSIGNEES or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereof;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEES thereof shall hereafter require and prepare at their own expense;

And I further agree that ASSIGNEES will, upon their request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereof;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: Serial Number _____, Filing Date _____.

This assignment executed on the dates indicated below.

Ralf Boehnke
Name of first or sole inventor Execution date of U.S. Patent Application

Esslingen, Germany
Residence of first or sole inventor

Ralf Boehnke 10. Jan 2000
Signature of first or sole inventor Date of this assignment

Kentaro Odaka
Name of second inventor Execution date of U.S. Patent Application

Tokyo, Japan
Residence of second inventor

Kentaro Odaka 1999.12.20
Signature of second inventor Date of this assignment

Hamid Amir-Alikhani
Name of third inventor Execution date of U.S. Patent Application

Leonberg, Germany
Residence of third inventor

H.A.A. 10. Jan. 2000 H.A.A.
Signature of third inventor Date of this assignment

Richard Stirling-Gallacher
Name of fourth inventor Execution date of U.S. Patent Application

Stuttgart, Germany
Residence of fourth inventor

R.D. Stirling-Gallacher 10.1.00
Signature of fourth inventor Date of this assignment

Seiichi Izumi
Name of fifth inventor Execution date of U.S. Patent Application

Fellbach, Germany
Residence of fifth inventor

Seiichi Izumi 10. Jan 2000
Signature of fifth inventor Date of this assignment

Mitsuhiro Suzuki

Name of sixth inventor

Execution date of U.S. Patent Application

Chiba, Japan

Residence of sixth inventor

Mitsuhiro Suzuki

Signature of sixth inventor

Dec 20, 1999

Date of this assignment